STARPOWER

SEMICONDUCTOR **IGBT**

GD35FSA120L2SMF

1200V/35A 6 in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as general inverters and UPS.

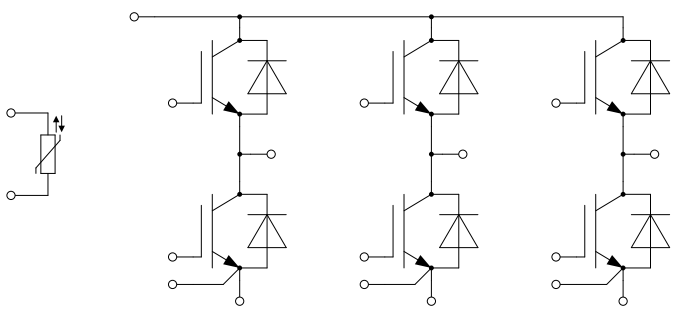
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- 8μs short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated heatsink using DBC technology
- PressFIT contact technology
- Pre-applied phase change material

Typical Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

Equivalent Circuit Schematic



Absolute Maximum Ratings T_H=25°C unless otherwise noted

IGBT

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	±20	V
I_C	Collector Current @ T_H=70°C	35	A
I_{CRM}	Repetitive Peak Collector Current tp limited by T_{vjop}	70	A

Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	35	A
I_{FRM}	Repetitive Peak Forward Current tp limited by T_{vjop}	70	A

Module

Symbol	Description	Value	Unit
T_{vjmax}	Maximum Junction Temperature	175	°C
T_{vjop}	Operating Junction Temperature	-40 to +175	°C
T_{STG}	Storage Temperature Range	-40 to +125	°C
V_{ISO}	Isolation Voltage RMS,f=50Hz,t=1min	2500	V

Note: T_{vjop} > 150°C is allowed for operation at overload conditions.

IGBT Characteristics T_H=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	I_C=35A,V_{GE}=15V, T_{vj}=25°C		1.50	1.95	V
		I_C=35A,V_{GE}=15V, T_{vj}=125°C		1.70		
		I_C=35A,V_{GE}=15V, T_{vj}=150°C		1.80		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	I_C=0.70mA,V_{CE}=V_{GE}, T_{vj}=25°C	5.4	6.2	7.0	V
I_{CES}	Collector Cut-Off Current	V_{CE}=V_{CES},V_{GE}=0V, T_{vj}=25°C			50	uA
I_{GES}	Gate-Emitter Leakage Current	V_{GE}=V_{GES},V_{CE}=0V, T_{vj}=25°C			100	nA
R_{Gint}	Internal Gate Resistance			0		Ω
C_{ies}	Input Capacitance	V_{CE}=25V,f=1MHz, V_{GE}=0V		3.09		nF
C_{res}	Reverse Transfer Capacitance			0.03		nF
Q_G	Gate Charge	V_{GE}=-15…+15V		0.22		μC

Diode Characteristics T_H=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	I_F=35A,V_{GE}=0V,T_{vj}=25°C		1.60	2.05	V
		I_F=35A,V_{GE}=0V,T_{vj}=125°C		1.65		
		I_F=35A,V_{GE}=0V,T_{vj}=150°C		1.65		

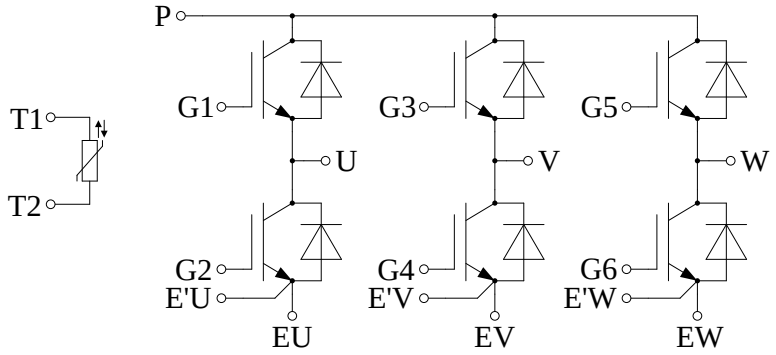
NTC Characteristics T_H=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			5.0		kΩ
ΔR/R	Deviation of R_{100}	T_C=100 °C,R_{100}=493.3Ω	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	R_2=R_{25}exp[$B_{25/50}$(1/T_2-1/(298.15K))]		3375		K
$B_{25/80}$	B-value	R_2=R_{25}exp[$B_{25/80}$(1/T_2-1/(298.15K))]		3411		K
$B_{25/100}$	B-value	R_2=R_{25}exp[$B_{25/100}$(1/T_2-1/(298.15K))]		3433		K

Module Characteristics T_H=25°C unless otherwise noted

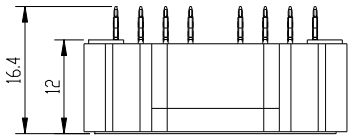
Symbol	Parameter	Min.	Typ.	Max.	Unit
L_{CE}	Stray Inductance		25		nH
$R_{CC'+EE'}$	Module Lead Resistance,Terminal to Chip		4.50		mΩ
R_{thJH}	Junction-to-Heatsink (per IGBT) Junction-to-Heatsink (per Diode)		1.270 1.810		K/W
F	Mounting Force Per Clamp	20		50	N
G	Weight of Module		24		g

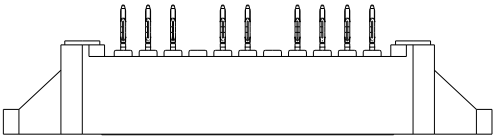
Circuit Schematic

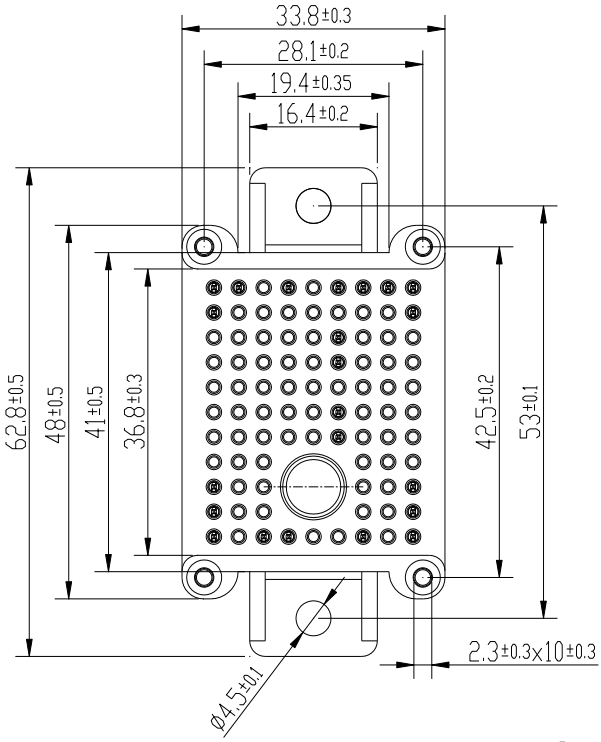


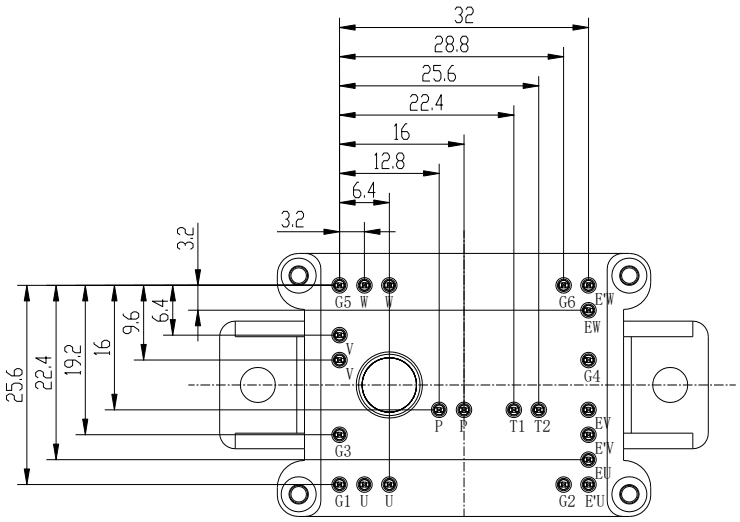
Package Dimensions

Dimensions in Millimeters









Pinpositions with tolerance ⌖ φ1.0

Terms and Conditions of Usage

The data contained in this product datasheet is exclusively intended for technically trained staff. you and your technical departments will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to such application.

This product data sheet is describing the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively pursuant the terms and conditions of the supply agreement. There will be no guarantee of any kind for the product and its characteristics.

Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of our product, please contact the sales office, which is responsible for you (see www.powersemi.cc), For those that are specifically interested we may provide application notes.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the Product in aviation applications, in health or live endangering or life support applications, please notify.

If and to the extent necessary, please forward equivalent notices to your customers.
Changes of this product data sheet are reserved.